

## 370HR Laminate 370HR Prepreg

370HR is a high performance 180°C glass transition temperature (Tg) FR-4 system for multilayer printed wiring board (PWB) applications where maximum thermal performance and reliability are required. 370HR laminate and prepreg products are manufactured with a unique high performance multifunctional epoxy resin, reinforced with electrical grade (E-glass) glass fabric. This system provides improved thermal performance and low expansion rates in comparison to traditional FR-4 while retaining FR-4 processability. In addition to this superior thermal performance the mechanical, chemical and moisture resistance properties all equal or exceed the performance of traditional FR-4 materials. The 370HR system is also laser fluorescing and UV blocking for maximum compatibility with automated optical inspection systems (AOI), optical positioning systems and photoimagable soldermask imaging.

#### **Industry Approvals**

IPC-4101B /21, /24, /26, /98, /99, /101, /126 UL Recognized – FR-4, File Number E45456 Qualified to UL's MCIL Program

#### **High Thermal Performance**

Tg of 180 C (DSC) Low CTE for reliability

#### **UV Blocking and AOI Fluorescence**

High throughput and accuracy during PCB fabrication and assembly

### **Superior Processing**

Closest to conventional FR-4 processing of all high speed materials

#### **Standard Availability**

**Thickness:** 0.002" [.05 mm] to 0.093" [2.4 mm]

Available in sheet or panel form

Copper Foil Cladding: Grade 3 (HTE), ½, 1 and 2 oz.

Foil Options: Reverse treat

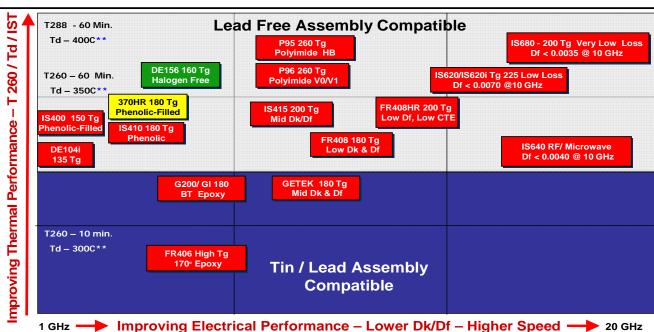
Prepregs: Available in roll or panel form

Glass Styles: standard fabrics



# Isola - Product Position Thermal Performance vs Signal Integrity





Speed is a function of design such as line length etc.

\*\* Laminate Data - IST performance is a function of Hole diameter, board thickness, plating parameters and laminate attributes.

		370HR			
Property		Typical Values			
				Units	Test Method IPC-TM-650 (or
		Typical Value	Specification	Metric (English)	as noted)
Glass Transition Temperature (Tg) by DSC, spec minimum		180	170-200	°C	2.4.25
Decomposition Temperature (Td) @ 5% wt loss		340	_	°C	ASTM D3850
T260 Deg C (TMA)		60	_	Min	ASTM D3850
T288 Deg C (TMA)		10		Min	ASTM D3850
CTE, Z-axis	A. Pre-Tg B. Post-Tg	45 230	AABUS —	ppm/°C	2.4.24
CTE, X-, Y-axes	A. Pre-Tg	13/14	AABUS	ppm/°C	2.4.24
	B. Post-Tg	14/17	_	* *	
% Z-Axis Expansion (50-260C)		2.8		%	2.4.24
Thermal Conductivity	I	0.4	— —	W/mK	ASTM D5930
Thermal Stress 10 Sec	A. Unetched	pass	Pass Visual	Rating	2.4.13.1
@ 288°C (550.4°F), spec min	B. Etched	pass	Pass Visual		0.5.5.0
	A. @ 100 MHz HP4285A	4.24	5.4		2.5.5.3
Permittivity, spec maximum	B. @ 1 GHz HP4291A C. @ 2 GHz Bereskin Stripline	4.17 4.04	_	_	2.5.5.9 2.5.5.5
(Laminate & prepreg as laminated)	C. @ 2 GHz Bereskin Stripline D. @ 5 GHz Bereskin Stripline	3.92			2.5.5.5
	E. @ 10 GHz Bereskin Stripline	3.92	_		2.5.5.5
	A. @ 100 MHz HP4285A	0.0150	0.035		2.5.5.3
Loss Tangent, spec maximum	B. @ 1 GHz HP4291A	0.0161	_		2.5.5.9
(Laminate & prepreg as laminated)	C. @ 2 GHz Bereskin Stripline	0.0210	_	_	2.5.5.5
(Lammato & proprog do lammatou)	D. @ 5 GHz Bereskin Stripline	0.0250	_		2.5.5.5
	E. @ 8 GHz Bereskin Stripline A. 96/35/90	0.0250	— — — — — — — — — — — — — — — — — — —		2.5.5.5
L	B. After moisture resistance	3x10 <sup>8</sup>	1.0 x10 <sup>6</sup>	Mo	05474
Volume Resistivity, spec minimum		7x10 <sup>8</sup>	4.0403	MΩ -cm	2.5.17.1
	C. At elevated temperature	7X10	1.0 x10 <sup>3</sup>		
Surface Resistivity, spec minimum	A. 96/35/90	3x10 <sup>6</sup>	1.0 x 10 <sup>4</sup>	Mo	0.5.47.4
Surface Resistivity, spec minimum		2x10 <sup>8</sup>	1.0 x 10 <sup>3</sup>	$M\Omega$	2.5.17.1
C. At elevated temperature			1.0 X 10		
Dielectric Breakdown, spec minimum		>50		kV	2.5.6
Arc Resistance, spec minimum		115	60	Seconds	2.5.1
Electric Strength, spec minimum (L	aminate & prepreg as laminated)	54	30	kV/mm	2.5.6.2
(-	ammate a propreg as tammatea,	1350	750	(V/mil)	
Comparative Tracking Index (CTI)		3 (175 - 249)	-	Class (volts)	UL-746A ASTM D3638
	A. Low profile copper foil and very low profile – all copper weights >17 microns	6.5(1.14)	4.0(0.70)	lb/inch(N/mm)	2.4.8
Peel Strength, Spec Minimum	B. Standard profile copper				2.4.8.2
•	After thermal stress	7.0(1.25)	4.5(0.8)		2.4.8.3
	2. At 125°C (257°F)	7.0(1.25)	4.0(0.70)	lb/inch(N/mm)	
	3. After process solutions	6.5(1.14)	3.0(0.55)		
Flexural Strength, minimum	A. Lengthwise direction     B. Crosswise direction	90,000 77,000	_	lb/inch <sup>2</sup>	2.4.4
Moisture Absorption, spec maximum		0.15	_	%	2.6.2.1
Flammability (Laminate & prepreg as laminated), spec min		V0		Rating	UL-94
HWI		0		, , ,	
Max Operating Temperature		130 (150)	UL Cert (tested)	Deg C	
DSR		yes	== = == (100.00)		
		yes			

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

ORDERING INFORMATION:
Contact your local sales representative or the Customer Service Department in Chandler, AZ Isola Group 3100 W Ray Road, Chandler, AZ 85226
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